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Technical Data Sheet

VieTape TIM4104

HIGH THERMALLY CONDUCTIVE GAP FILLER PAD

DESCRIPTION

High thermal conductive gap filler pad that has low thermal resistance and excellent electrical insulation at low compression. It can work stably at -60°C~200°C

APPLICATIONS

Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, ...

TYPICAL PERFORMANCE PROPERTIES

PROPERTIES	VALUE	METHOD
Appearance	Purple	Visual
Thickness	0.5-10.0 mm	ASTM D374
Density	3.1 g/cm^3	ASTM D792
Working Temperature	-60 to 200^{0}C	-
Hardness	50-60 shore 00	ASTM D2240
ELECTRICAL PROPERTIES		
Breakdown Voltage	>6.0 kV/mm	ASTM D149
Volume Resistivity	10^{13} Ohm-cm	ASTM D257
Dielectric Constant@1MHz	7.0	ASTM D150
THERMAL PROPERTIES		
Thermal conductivity	4.0 W/m.K	ISO22007-2
Flammability	Meet UL94-V0	

SHELF LIFE AND STORAGE

12 months from date of manufacture when stored at 10 - 30°C and 40 - 50% relative humidity. Avoid extrusion and exposure to the sun.

CAUTION

For safe handling information on this product, please review the Safety Data Sheet, SDS

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